New crystal-clear UV adhesive for semiconductor production

At this year’s BondExpo Panacol will present Vitralit® UC 1535, a new transparent adhesive specifically designed for use in electronics. It hardens with UV light within a few seconds and can be used for semiconductor production due to its low ion content.

The Vitralit® UC 1535 is an epoxy-based UV-curing adhesive that hardens very fast. It is easy to dispense and non shear-thinning. In just a few seconds, the adhesive can be cured with radiation in the UVA range from 320 to 390 nm. For a fast and efficient curing, the broad spectrum and UV/LED systems from Dr. Hoenle AG are highly recommended.

The adhesive was especially designed for the assembly and production of electronic and optomechanical components. For example, the new Vitralit® UC 1535 is being used to bond glass lenses in optical systems. Once cured the adhesive features a transparent, optically clear and brilliant surface, which is very hard and scratch-resistant. Vitralit® UC 1535 is non-yellowing and remains optically clear even when exposed to high temperatures. Because of its low ion content the adhesive can be used for semiconductor applications.

Visit us at the BondExpo in Stuttgart, Germany from the 7th to the 10th of October 2019 at booth 6420 in hall 6!

About Panacol:
Panacol-Elosol GmbH, a member of the global Hoenle group, is an international supplier of adhesives with an extensive product range that includes UV curable adhesives, structural adhesives, and conductive adhesives. Panacol is also a reliable provider of UV processing systems, supported by Dr. Hoenle AG. Hoenle is a global technology leader and manufacturer of industrial UV curing devices and systems.